

LL056BT35135

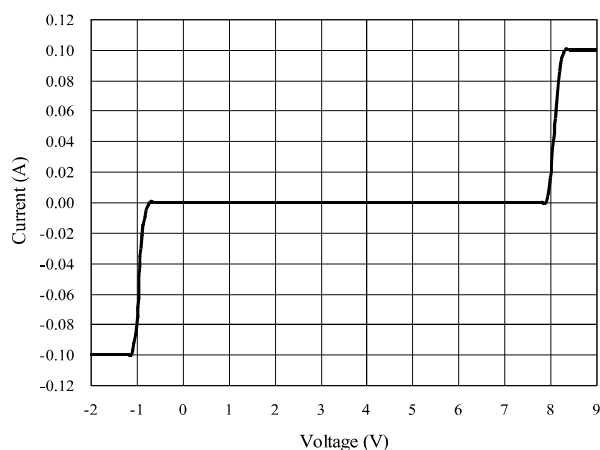
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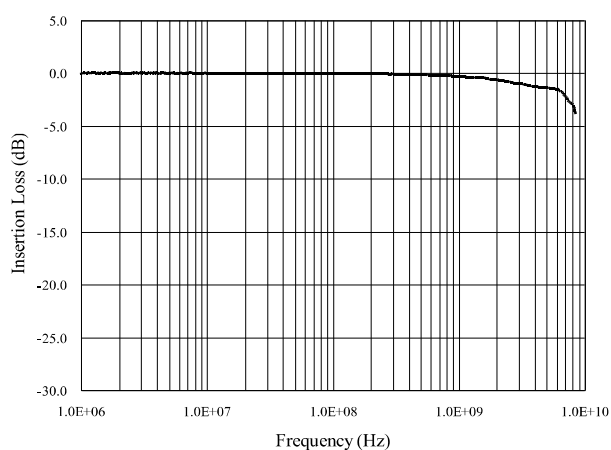
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Rating and characteristic curves

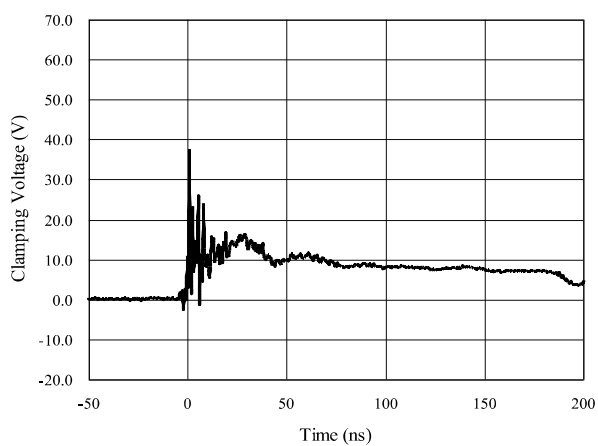
Voltage Sweeping of I/O to GND



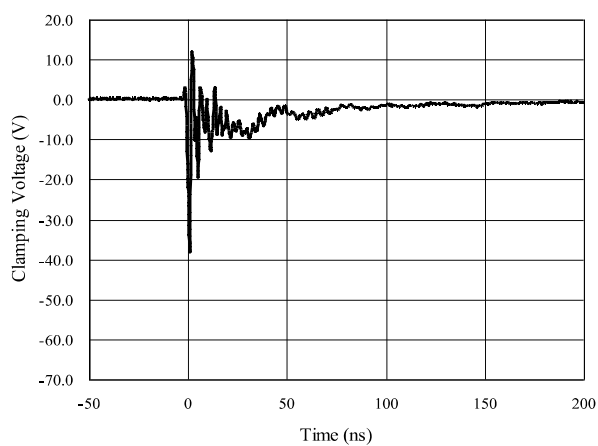
Insertion Loss S21 of I/O to GND



ESD Clamping of I/O to GND (+8kV Contact per IEC 61000 -4-2)



ESD Clamping of I/O to GND (-8kV Contact per IEC 61000 -4-2)

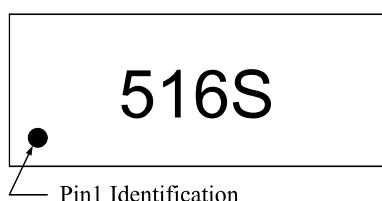


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Pinning information

Pin Configuration	Simplified outline	Circuit Diagram
1, 2, 3, 4, 6, 7 NC 8, 9, 11, 12, 13, 14 I/O Line 5, 10 Ground		

Marking

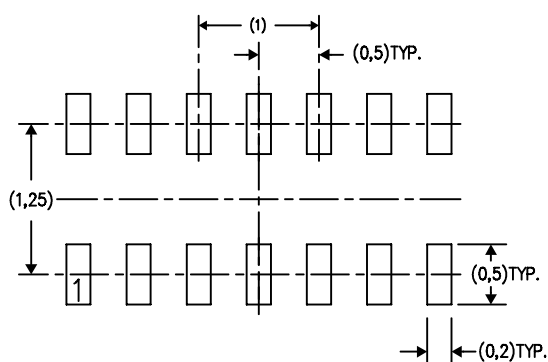


Pin1 Identification

Note:

(1) “516S” is part number, fixed.

Suggested solder pad layout

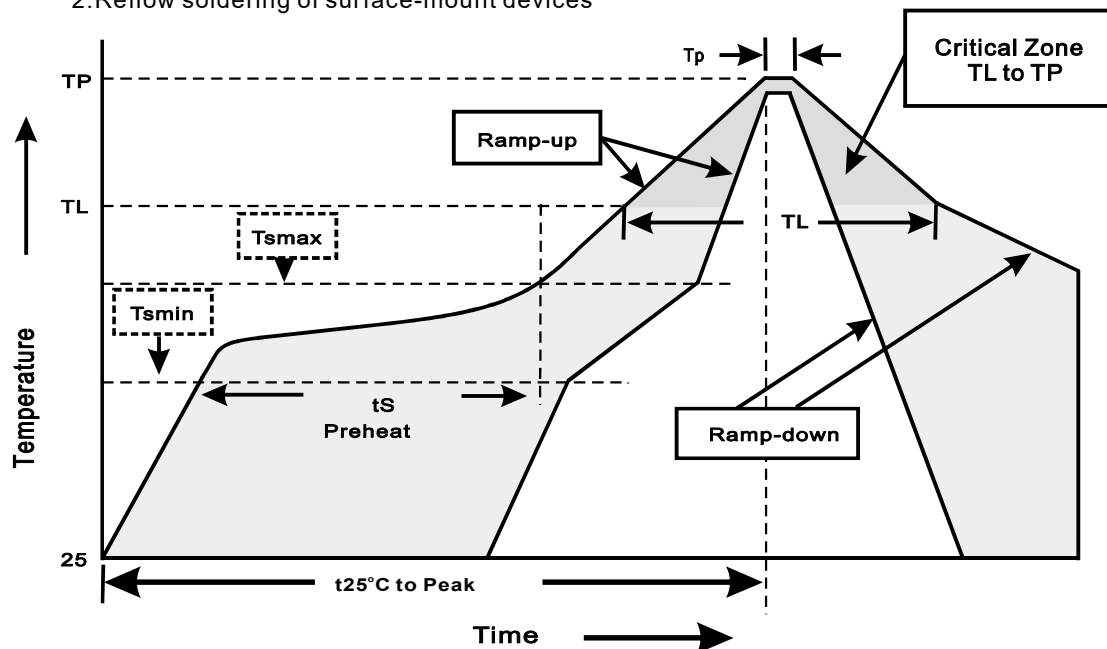


Dimensions in millimeters

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Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes